TP(P12)Mini2II. Gen

MiniSKiiP®

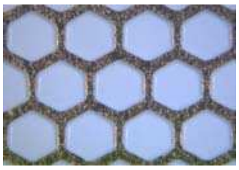
Pre applied thermal paste

Wacker P12 (silicone based)

TP(P12)Mini2II. Gen

Features

- Honeycomb structure
- Optimized thickness of thermal paste layer
- Enhanced heat dissipation
- High process reliability due to automated screen printing process



honeycomb structure

Symbol	Conditions	min.	typ.	max.	Unit
Characteristics of printing process					
d_{tp}	thickness of thermal paste	45	55	65	µm
Storage conditions					
t_{stg}	storage time			18	month
T_{stg}	storage temperature	-25		60	°C
RH_{stg}	storage humidity	10		95	%
Characteristics of thermal paste					
γ_{tp}	specific gravity		2.25		g/cm^3
R_{tp}	resistivity		$1*10^{13}$		Ω/cm
E_{tp}	dielectric strength		20		kV/cm
λ_{tp}	thermal conductivity		0.8		W/ (K*m)

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.